

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Please amend the claims as follows:

1. (Currently Amended) A resin composition for encapsulating a semiconductor chip comprising:

an epoxy resin (A);

a phenol resin (B);

an inorganic filler (C);

a curing accelerator (D);

a silane coupling agent (E); and

Compound (F) containing two and or more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring,

wherein the epoxy resin (A) is a member selected from the group consisting of phenol novolac type epoxy resins, cresol novolac type epoxy resins, biphenyl type epoxy resins, bisphenol type epoxy resins, stilbene type epoxy resins, triphenolmethane type epoxy resins, phenolaralkyl (including a phenylene or biphenylene structure) type epoxy resins, naphthol type epoxy resins, alkyl-modified triphenolmethane type epoxy resins, triazine-structure containing type epoxy resins, dicyclopentadiene-modified phenol type epoxy resins, and mixtures thereof.

2. (Currently Amended) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein ~~the resin composition comprises~~ said compound (F) in is present in an amount more than or equal to 0.01 wt%.

3. (Currently Amended) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said silane coupling agent (E) in an amount of 0.01 wt% to 1 wt% both inclusive.

4. (Currently Amended) ~~The A~~ resin composition for encapsulating a semiconductor chip ~~according to Claim 1 comprising:~~

an epoxy resin (A);

a phenol resin (B);

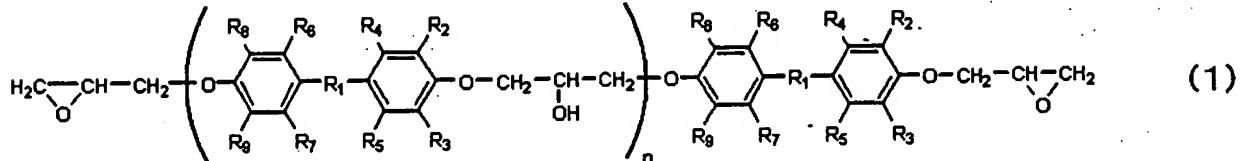
an inorganic filler (C);

a curing accelerator (D);

a silane coupling agent (E); and

Compound (F) containing two or more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring,

wherein said epoxy resin (A) comprises an epoxy resin represented by general formula (1):



wherein R₁ represents a single bond or saturated or unsaturated hydrocarbon having up to three carbon atoms; R₂ to R₉, which may be the same or different from each other, represent hydrogen or saturated hydrocarbon having up to four carbon atoms; and n is a positive number more than 0 and up to 5 as an average, in 50 wt% or more.

5. (Original) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said aromatic ring.

6. (Original) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the aromatic ring is a naphthalene ring.

7. (Original) The resin composition for encapsulating a semiconductor chip according to Claim 6, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said naphthalene ring.

8. (Currently Amended) The resin composition for encapsulating a semiconductor chip according to ~~Claims~~ Claim 1, wherein the resin composition comprises said inorganic filler (C) in an amount of 80 wt% to 94 wt% both inclusive.

9. (Currently Amended) A semiconductor device wherein a semiconductor chip is encapsulated by ~~the use of a~~ the resin composition ~~for encapsulating a semiconductor chip~~ according to ~~Claims~~ Claim 1.

10. (New) The resin composition for encapsulating a semiconductor chip according to Claim 4, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said aromatic ring.

11. (New) The resin composition for encapsulating a semiconductor chip according to Claim 4, wherein the aromatic ring is a naphthalene ring.

12. (New) The resin composition for encapsulating a semiconductor chip according to Claim 11, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said naphthalene ring.

13. (New) The resin composition for encapsulating a semiconductor chip according to Claim 4, wherein the resin composition comprises said inorganic filler (C) in an amount of 80 wt% to 94 wt% both inclusive.

14. (New) A semiconductor device wherein a semiconductor chip is encapsulated by the resin composition according to Claim 4.